

## RKD701KN

### Silicon Schottky Barrier Diode for High Speed Switching

REJ03G1471-0100

Rev.1.00

Sep 27, 2006

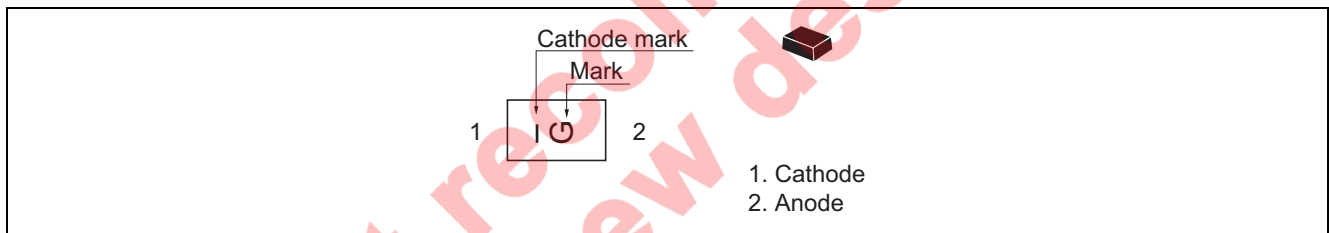
#### Features

- Low reverse current, Low capacitance.
- A free halogen has corresponded.
- Ultra small leadless Package (0805type; the use of an undersurface electrode structure) for use in compact and products.

#### Ordering Information

Type No.	Laser Mark	Package Name	Package Code
RKD701KN	G	MP8	PXSN0002ZA-A

#### Pin Arrangement



## Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	$V_{RRM}$	25	V
Non-Repetitive Peak forward surge current	$I_{FSM}^*$	200	mA
Forward current	$I_F$	50	mA
Junction temperature	$T_j$	125	°C
Storage temperature	$T_{stg}$	-55 to +125	°C

Note: 10 ms Sine Wave 1 pulse

## Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	$V_{F1}$	—	—	0.33	V	$I_F = 1 \text{ mA}$
	$V_{F2}$	—	—	0.38		$I_F = 5 \text{ mA}$
Reverse current	$I_R$	—	—	450	nA	$V_R = 20 \text{ V}$
Capacitance	C	—	—	2.80	pF	$V_R = 1 \text{ V}, f = 1 \text{ MHz}$

Note: Please do not use the soldering iron due to avoid high stress to the MP8 package.

Not recommended for new design

Main Characteristic

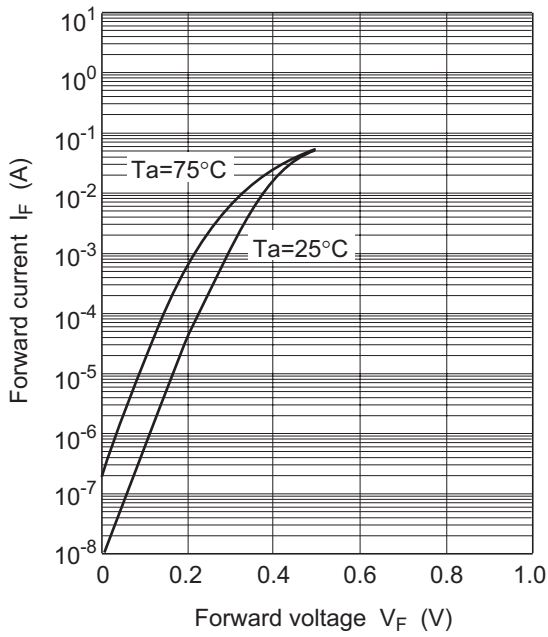


Fig.1 Forward current vs. Forward voltage

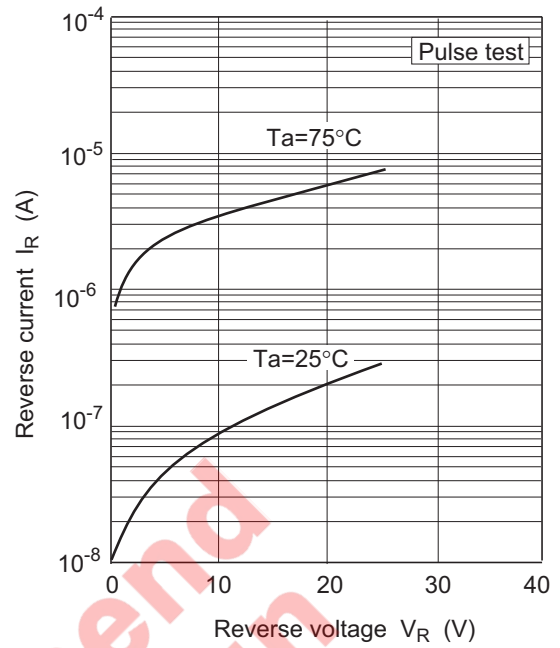


Fig.2 Reverse current vs. Reverse voltage

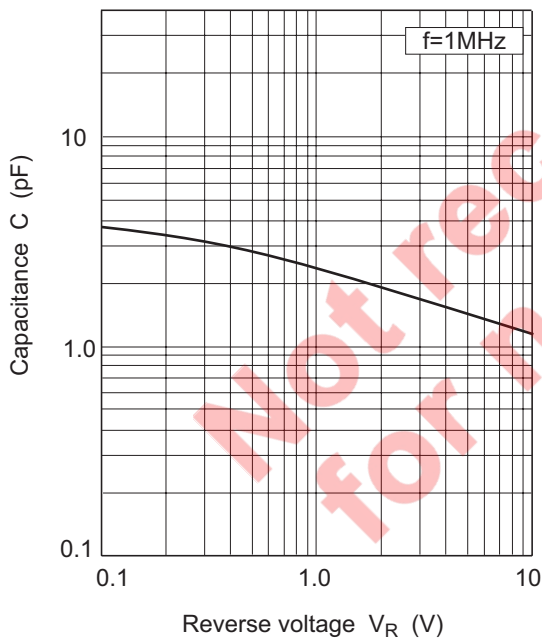
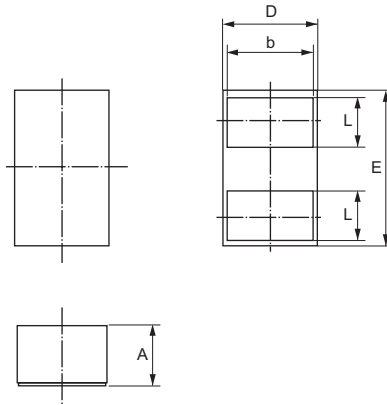


Fig.3 Capacitance vs. Reverse voltage

### Package Dimensions

Package Name	JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
MP8	—	PXSN0002ZA-A	MP8V	0.00029g



Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
A	0.27	0.30	0.33
b	0.38	0.40	0.42
D	0.47	0.50	0.53
E	0.77	0.80	0.83
L	0.23	0.25	0.27

Not recommend for new design

Notes:

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